

Gate resistor installed Dual N-channel MOSFET

KFCAB21A50L Data Sheet

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1. GENERAL DESCRIPTION

Gate resistor installed Dual N-channel MOSFET

For lithium-ion secondary battery protection circuits

2. FEATURES

- Source-source On-state resistance: $R_{SS}(\text{on})$ typ. = $2.2\text{ m}\Omega$ ($V_{GS} = 3.8\text{ V}$)
- CSP (Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1)

3. MARKING SYMBOL: UA

4. PACKAGING

Embossed type (Thermo-compression sealing): 10,000 pcs / reel (standard)

5. ABSOLUTE MAXIMUM RATINGS $T_a = 25\text{ }^{\circ}\text{C}$

Parameter		Symbol	Rating	Unit
Source-source Voltage		VSS	12	V
Gate-source Voltage		VGS	± 8	V
Source Current	DC *1	IS1	13.5	A
	DC *2	IS2	25	
	DC *3	IS3	29	
	Pulsed *4	ISp	135	
Total Power Dissipation	DC *1	PD1	0.54	W
	DC *2	PD2	1.8	
	DC *3	PD3	3.5	
Channel Temperature		Tch	150	$^{\circ}\text{C}$
Storage Temperature Range		Tstg	-55 to +150	$^{\circ}\text{C}$

6. THERMAL CHARACTERISTICS $T_a = 25\text{ }^{\circ}\text{C}$

Parameter	Symbol	Rating	Unit
Thermal Resistance (ch-a)	Rth1 *1	231	$^{\circ}\text{C} / \text{W}$
	Rth2 *2	69.0	
	Rth3 *3	35.5	

Note *1 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).

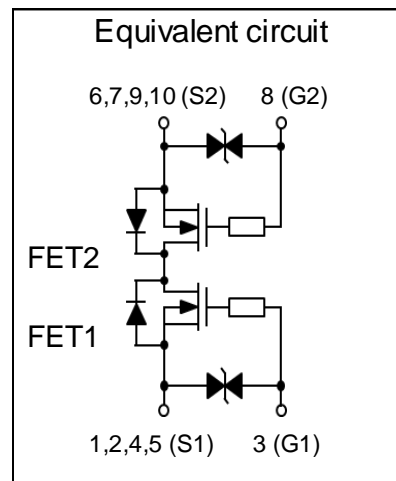
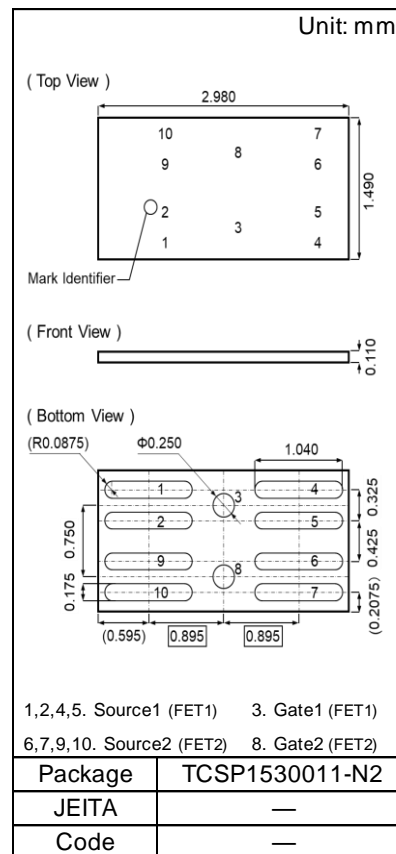
FR4 board partially covered with copper pad (42 mm² area, 36 μm thickness).

*2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).

FR4 board fully covered with copper pad (602 mm² area, 36 μm thickness).

*3 Mounted on Ceramic board (70 mm x 70 mm x t1.0 mm).

*4 $t = 10\text{ }\mu\text{s}$, Duty Cycle $\leq 1\%$.



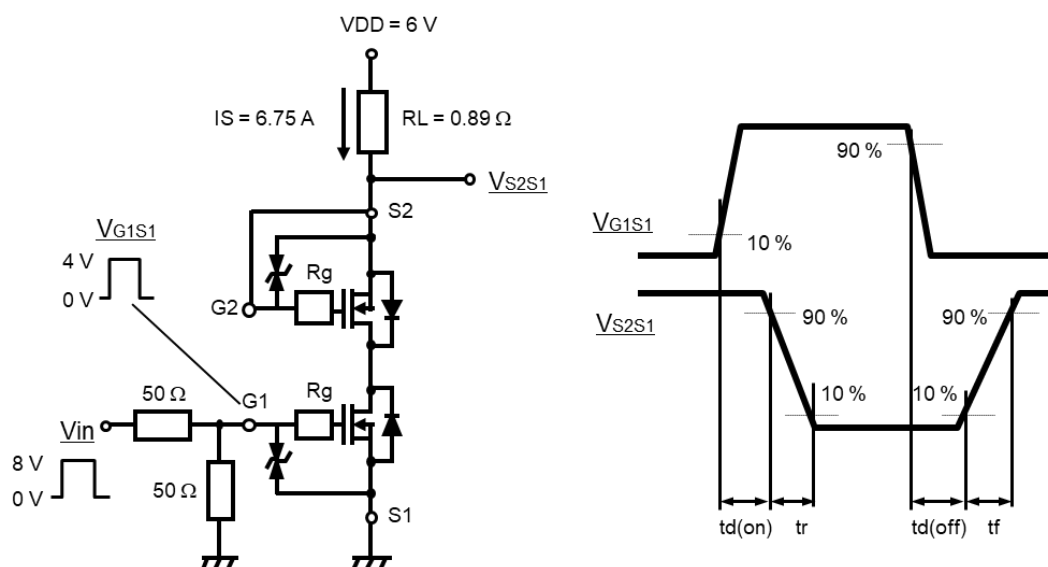
7. ELECTRICAL CHARACTERISTICS $T_a = 25\text{ }^{\circ}\text{C} \pm 3\text{ }^{\circ}\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Source-source Breakdown Voltage	VSSS	$I_S = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	12			V
Zero Gate Voltage Source Current	ISSS	$V_{SS} = 12\text{ V}$, $V_{GS} = 0\text{ V}$			1.0	μA
Gate-source Leakage Current	IGSS1	$V_{GS} = \pm 8\text{ V}$, $V_{SS} = 0\text{ V}$			± 10	μA
	IGSS2	$V_{GS} = \pm 5\text{ V}$, $V_{SS} = 0\text{ V}$			± 1.0	
Gate-source Threshold Voltage	V_{th}	$I_S = 0.79\text{ mA}$, $V_{SS} = 6\text{ V}$	0.35	0.90	1.40	V
Source-source On-state Resistance	RSS(on)1	$I_S = 6.75\text{ A}$, $V_{GS} = 4.5\text{ V}$	1.55	2.10	2.75	$\text{m}\Omega$
	RSS(on)2	$I_S = 6.75\text{ A}$, $V_{GS} = 3.8\text{ V}$	1.60	2.20	2.85	
	RSS(on)3	$I_S = 6.75\text{ A}$, $V_{GS} = 3.1\text{ V}$	1.65	2.40	3.95	
	RSS(on)4	$I_S = 6.75\text{ A}$, $V_{GS} = 2.5\text{ V}$	1.90	3.10	6.10	
Body Diode Forward Voltage	$V_{F(s-s)}$	$I_F = 6.75\text{ A}$, $V_{GS} = 0\text{ V}$		0.7	1.0	V
Input Capacitance *1	Ciss	$V_{SS} = 10\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ kHz}$		4270		pF
Output Capacitance *1	Coss			690		
Reverse Transfer Capacitance *1	Crss			590		
Turn-on Delay Time *1,*2	$t_{d(on)}$	$V_{DD} = 6\text{ V}$, $V_{GS} = 0\text{ to }4\text{ V}$		1.4		μs
Rise Time *1,*2	t_r	$I_S = 6.75\text{ A}$		2.5		
Turn-off Delay Time *1,*2	$t_{d(off)}$	$V_{DD} = 6\text{ V}$, $V_{GS} = 4\text{ to }0\text{ V}$		6.0		μs
Fall Time *1,*2	t_f	$I_S = 6.75\text{ A}$		3.4		
Total Gate Charge *1	Qg	$V_{DD} = 6\text{ V}$		33		nC
Gate-source Charge *1	Qgs	$V_{GS} = 0\text{ to }4\text{ V}$		11		
Gate-drain Charge *1	Qgd	$I_S = 13.5\text{ A}$		6.0		

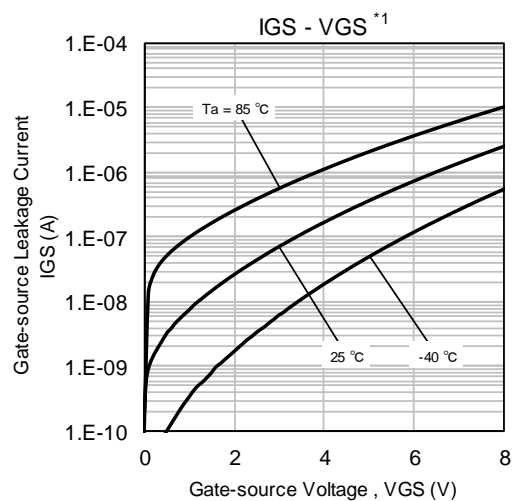
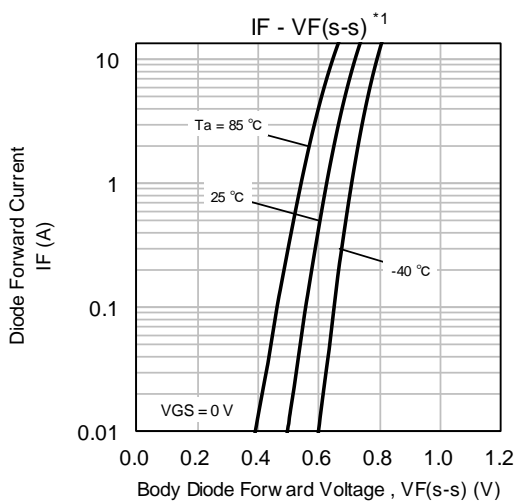
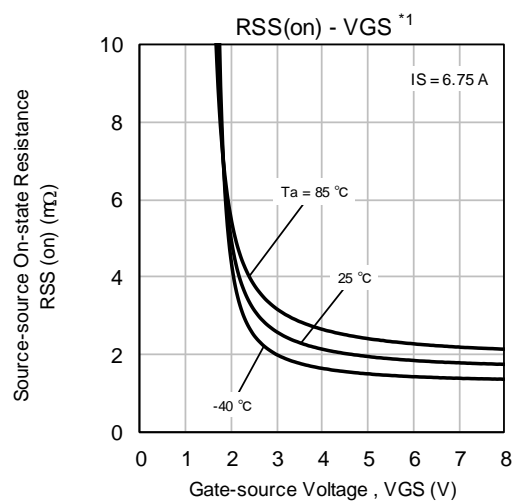
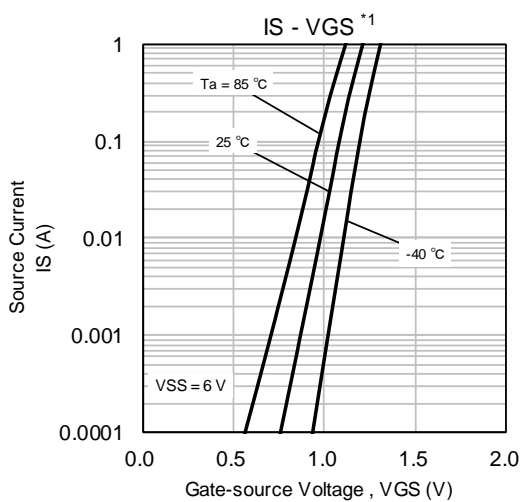
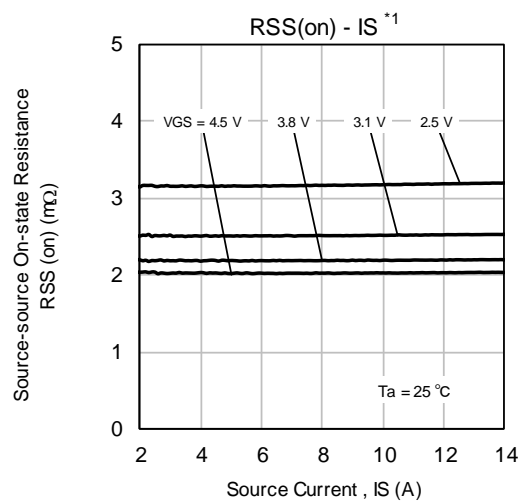
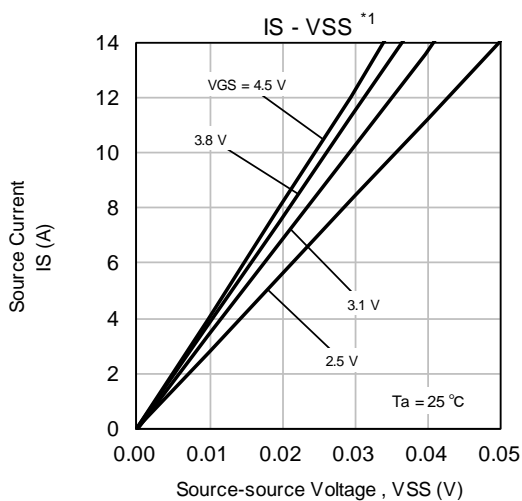
Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

*1 Guaranteed by design, not subject to production testing

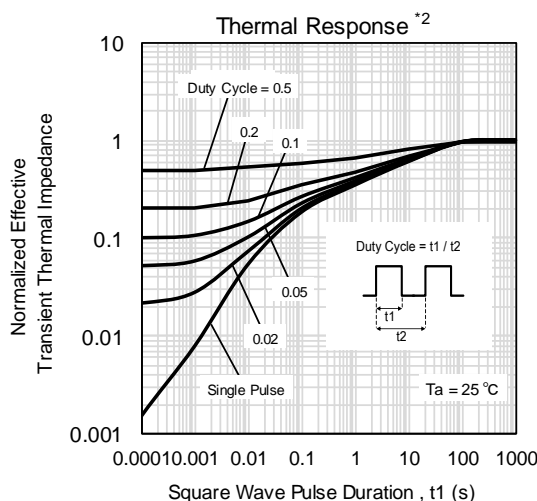
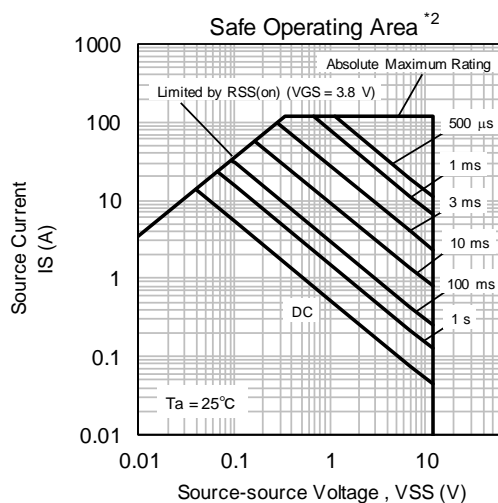
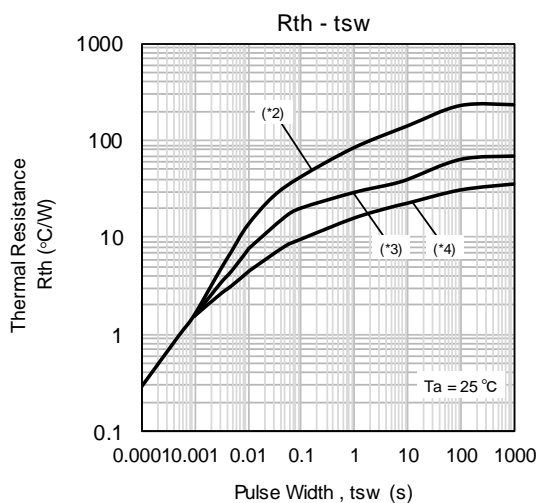
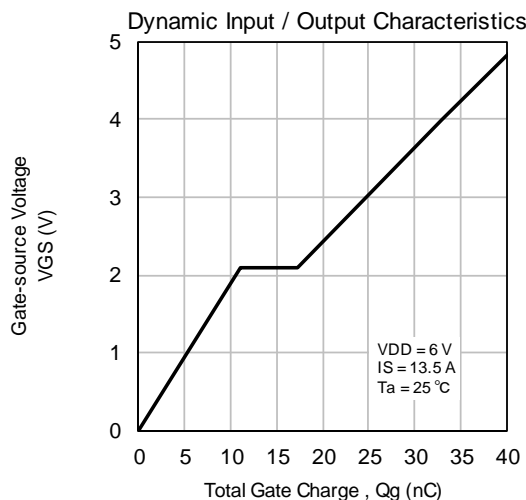
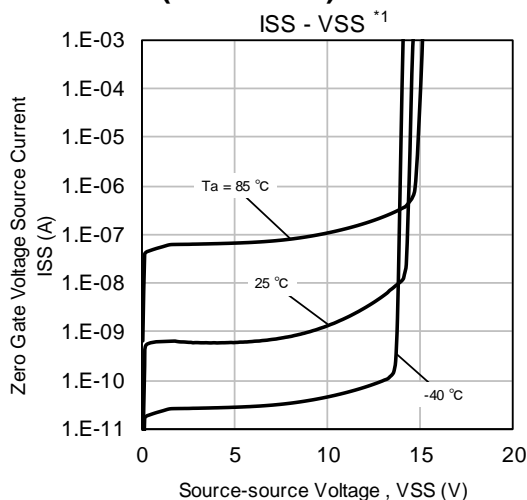
*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time



8. TECHNICAL DATA (Reference)



TECHNICAL DATA (Reference)



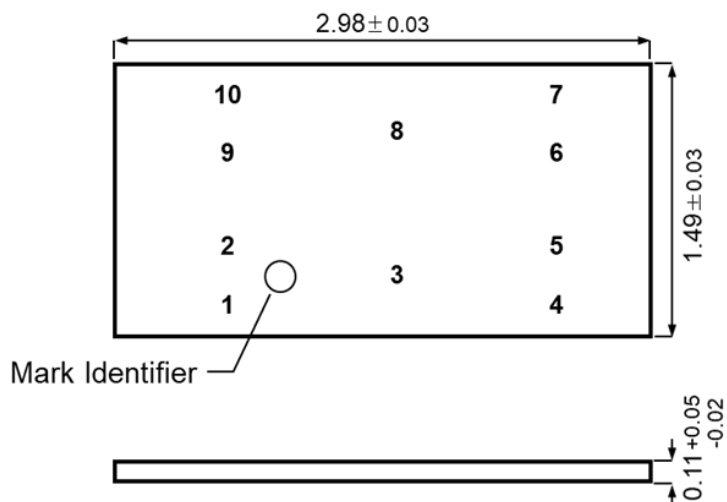
Note

- *1 Pulse measurement.
- *2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board partially covered with copper pad
(42 mm² area, 36 μm thickness).
- *3 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board fully covered with copper pad
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- *4 Mounted on ceramic board (70 mm x 70 mm x t1.0 mm).

9. OUTLINE

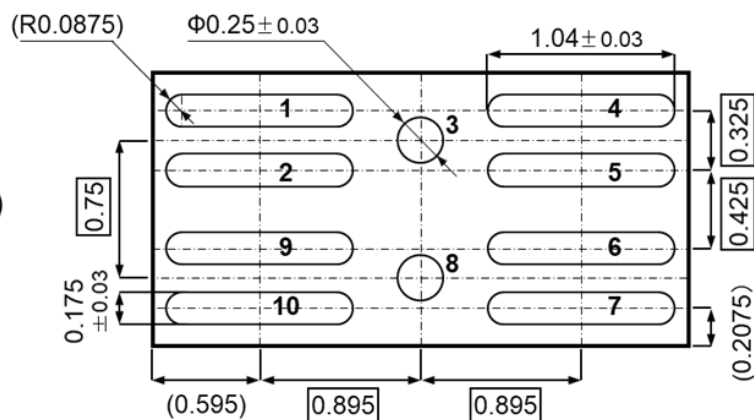
Unit : mm

(Top View)



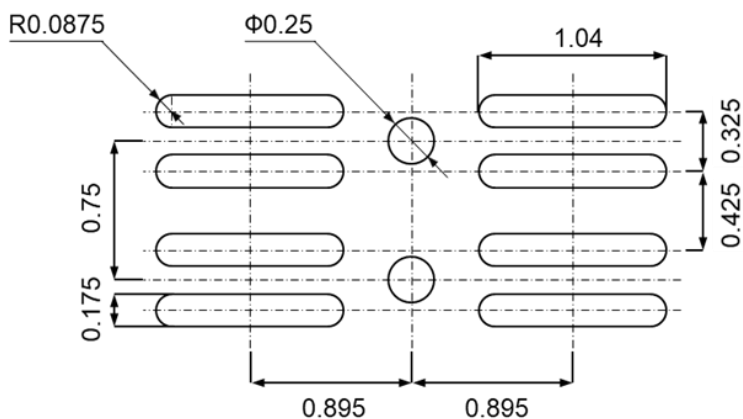
(Front View)

(Bottom View)



10. LAND & STENCIL PATTERN (Reference)

Unit : mm



11. REVISION HISTORY

Date	Revision	Description
2021.2.10	1.00	1. initially issued.

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